



Product Change Notification / MFOL-01NFYM899

Date:

02-May-2023

Product Category:

Linear Regulators

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5227 Final Notice: Qualification of MMT as an additional assembly site for MIC37303YML-T5 and MIC37303YML-TR catalog part numbers (CPN) available in 8L VDFN (3x3x0.9mm) package.

Affected CPNs:

[MFOL-01NFYM899_Affected_CPN_05022023.pdf](#)
[MFOL-01NFYM899_Affected_CPN_05022023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MMT as an additional assembly site for MIC37303YML-T5 and MIC37303YML-TR catalog part numbers (CPN) available in 8L VDFN (3x3x0.9mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
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Assembly Site		Unisem (M) Berhad Perak, Malaysia (UNIS)	Unisem (M) Berhad Perak, Malaysia (UNIS)	Microchip Technology Thailand (Branch) (MMT)
Wire Material		Au	Au	Au
Die Attach Material		8290	8290	8600
Molding Compound Material		G770HCD	G770HCD	G700LTD
Lead-Frame Material		A194	A194	A194
Lead-Frame	Paddle Size	71x98 mils	71x98 mils	71x102 mils
	Lead-lock	No	No	Yes
DAP Surface Prep		NiPdAu-PPF	NiPdAu-PPF	NiPdAu-PPF

Impacts to Data Sheet:Update package max. thickness to 1.0mm.

POD Comparison (8 VDFN 3x3mm-JMA)							
Unit: mm		UNIS			MMT		
SYMBOL	DESCRIPTION	MIN	NOM	MAX	MIN	NOM	MAX
A	Overall Thickness	0.80	0.85	0.90	0.80	0.90	1.0
A1	Stand-off	0.00	-	0.05	0.00	-	0.05
A3	LF thickness	0.203 REF			0.203 REF		
D	Overall package width	2.95	3.00	3.05	3.00 BSC		
E	Overall package length	2.95	3.00	3.05	3.00 BSC		
e	Lead Pitch	0.65 BSC			0.65 BSC		
D2	Exposed Pad Width	1.50	1.55	1.60	1.50	1.55	1.60
E2	Exposed Pad Length	2.25	2.30	2.35	2.25	2.30	2.35
L	Terminal Length	0.35	0.40	0.45	0.35	0.40	0.45
b	Terminal Width	0.20	0.25	0.30	0.20	0.25	0.30
K	Terminal-to-Exposed pad	-	-	-	0.20	-	-

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:May 20, 2023 (date code: 2320)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2022					>	May 2023				
Workweek	4 5	4 6	4 7	4 8	4 9		1 8	1 9	2 0	2 1	2 2
Initial PCN Issue Date	x										
Qual Report Availability							x				
Final PCN Issue Date							x				
Estimated Implementation Date									x		

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:November 04, 2022: Issued initial notification.

May 2, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on May 20, 2023.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_MFOL-01NFYM899_Qual_Report.pdf](#)

[PCN_MFOL-01NFYM899_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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